

February 24, 2012

Announcement of Organizational Changes

JX Nippon Mining & Metals Corporation (head office: Otemachi 2-chome, Chiyoda-ku, Tokyo; president: Masanori Okada) has adopted the organizational changes indicated below effective April 1. The changes are designed to achieve more efficient and streamlined operations as customers increasingly move their manufacturing overseas, the yen remains at a high exchange rate, and the business environment for electronic materials processing grows more challenging.

The changes are as follows.

1. In the Functional Materials Division, the Electro-deposited Copper Foil Department and the Treated Rolled Copper Foil Department will be merged to form the Copper Foil Department.

In existing fields, the copper foil market is becoming increasingly compartmentalized between electro-deposited copper foil and treated rolled copper foil. In new fields, however, customer needs are diversifying, making it desirable to have a marketing organization that can flexibly propose solutions involving either electro-deposited copper foil or treated rolled copper foil. Considering these customer needs, we are integrating the two departments so as to achieve greater efficiency of operations related to both electro-deposited and treated rolled copper foil.

2. In the Thin Film Materials Division, the Semiconductor Department and the FPD Department will be merged to form the Sputtering Target Department.

Sputtering targets for semiconductors and those for flat panel displays are being supplied to the same major customers. Moreover, both kinds of sputtering targets are used in manufacturing many end products. In light of this situation, we decided to merge the two departments so that we will be able to serve customer needs more effectively and quickly by sharing information concerning semiconductor targets and FPD targets, and by carrying out integrated operations.